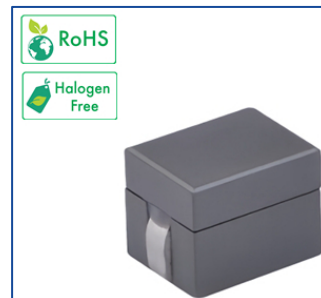
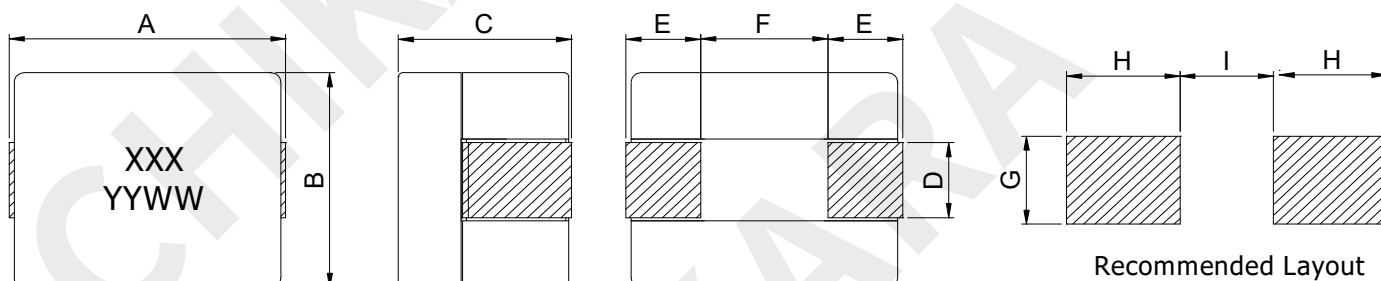


Features

- Magnetically shielded construction
- Storage temperature range:-55°C to + 130°C
- Operating temperature range:-55°C to + 130°C
(including coil's self-temperature rise)
- Moisture sensitivity level:1
- Packaging:700pcs. Per 13-inch reel
- RoHs&Halogen-free compliant



Mechanical Dimension(Unit:mm)



A	B	C	D	E	F	G	H	I
10.41Max.	8.0Max.	7.5Max.	2.25±0.2	2.54±0.2	5.12±0.3	2.5	3.0	4.7

Part Number Description

SP20 - 105075 R12 K
① ② ③ ④

①	Type
②	Dimensions
③	Inductance value
④	Tolerance code

Electrical Schematic

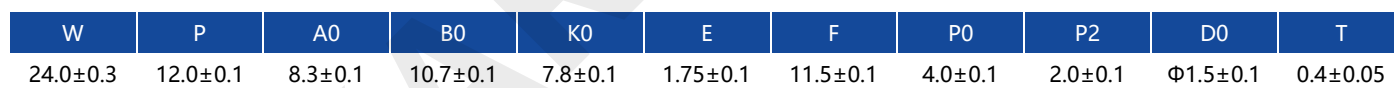


Electrical Characteristic

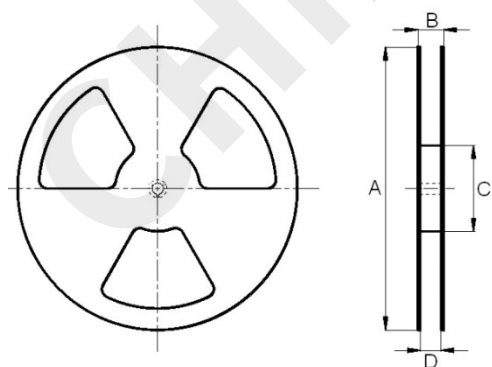
Part Number	Inductance L0(uH)	DCR (mΩ)±5%	Isat ¹ (A)Typ.@25°C	Isat ² (A)Typ.@45°C	Isat ³ (A)Typ.@100°C	Irms (A)Typ.
SP20-105075R12K	0.12±10%	0.29	94.0	90.0	76.0	61
SP20-105075R15K	0.15±10%	0.29	80.0	76.0	67.0	61
SP20-105075R17K	0.17±10%	0.29	72.0	69.0	60.0	61
SP20-105075R20K	0.20±10%	0.29	62.0	59.0	52.0	61
SP20-105075R21L	0.21±15%	0.29	55.0	52.0	50.0	61
SP20-105075R23L	0.23±15%	0.29	54.0	50.0	42.0	61
SP20-105075R26K	0.26±10%	0.29	47.0	45.0	38.0	61
SP20-105075R27L	0.27±15%	0.29	42.0	39.0	35.0	61
SP20-105075R30L	0.30±15%	0.29	39.0	38.0	32.0	61

- Test frequency and voltage:100KHz,0.1Vrms.
- All test data referenced to 25°C ambient(unless otherwise noted).
- Saturation current(Isat¹&Isat²&Isat³) will cause L0 to drop approximately 20%.
- Heat rated current(Irms) will cause the coil temperature rise approximately Δt of 40°C.
- Heat rated current (Irms) is tested on a typical PCB and apply a constant current in still air. The temperature rise is dependent on the application system condition including PCB PAD pattern, trace width and thickness and adjacent components etc. It' s suggested to verify the temperature rise of the component under the real operation application conditions.

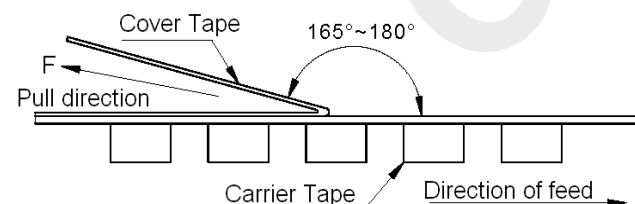
- Carrier Tape (Unit:mm)



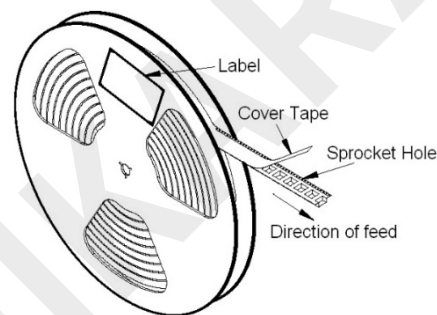
A	B	C	D
$\Phi 330 \pm 1.0$	28.9Max.	$\Phi 100 \pm 1.0$	24.5 ± 0.5



Peel-off strength	Peel-off angle	Peel-off speed
F=0.1N~1.3N	165°~180°	300mm/min.



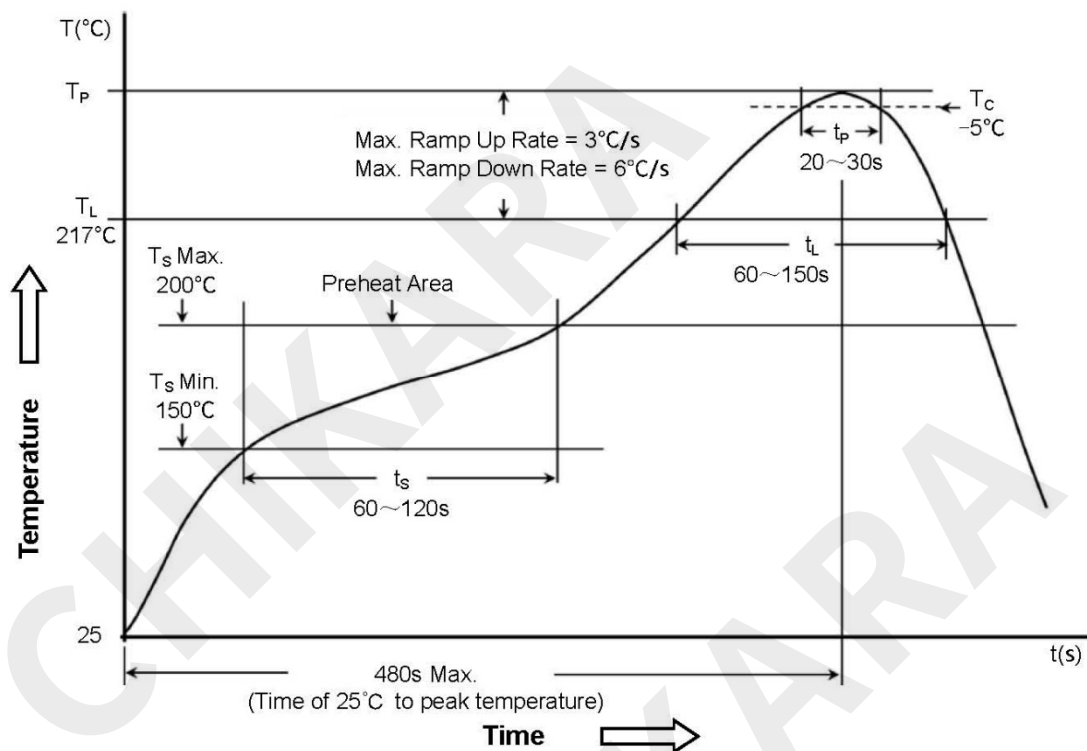
✖ Packing is referred to the international standard IEC 60286-3.



700Pcs

Soldering Specification

- Reflow profile for SMT components



- Classification of peak package body temperature (Tp)

	Package Thickness	Package Volume		
		<350mm ³	350~2000mm ³	>2000mm ³
PB-Free Assembly	<1.6mm	260°C	260°C	260°C
	1.6~2.5mm	260°C	250°C	245°C
	≥2.5mm	250°C	245°C	245°C

※ Reflow is referred to standard IPC/JEDEC J-STD-020D.